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Application Number:	10603257			
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Title of Invention:	Method for making a direct chip attach device and structure			
First Named Inventor:	Yeu Wen Lee			
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Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Amendment After Final	AmendmentAfterFinalONS00 461.pdf	306493	no	8
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New Applications Under 35 U.S.C. 111

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National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.